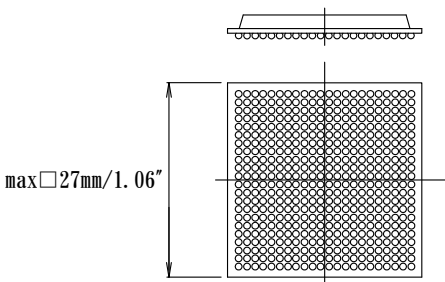


**Test & Burn-In Socket, GU66 molded frame series**  
**Size 58x66mm / 2.29x2.60"**

- Features:
- High reliability
  - Cost competitive
  - Short delivery time
  - Temperature  
-40°C to +150°C  
(typical)

● Acceptable device size



max □ 27mm/1.06"

In the case of larger size, consult factory.  
Any device on 0.30mm pitch or larger

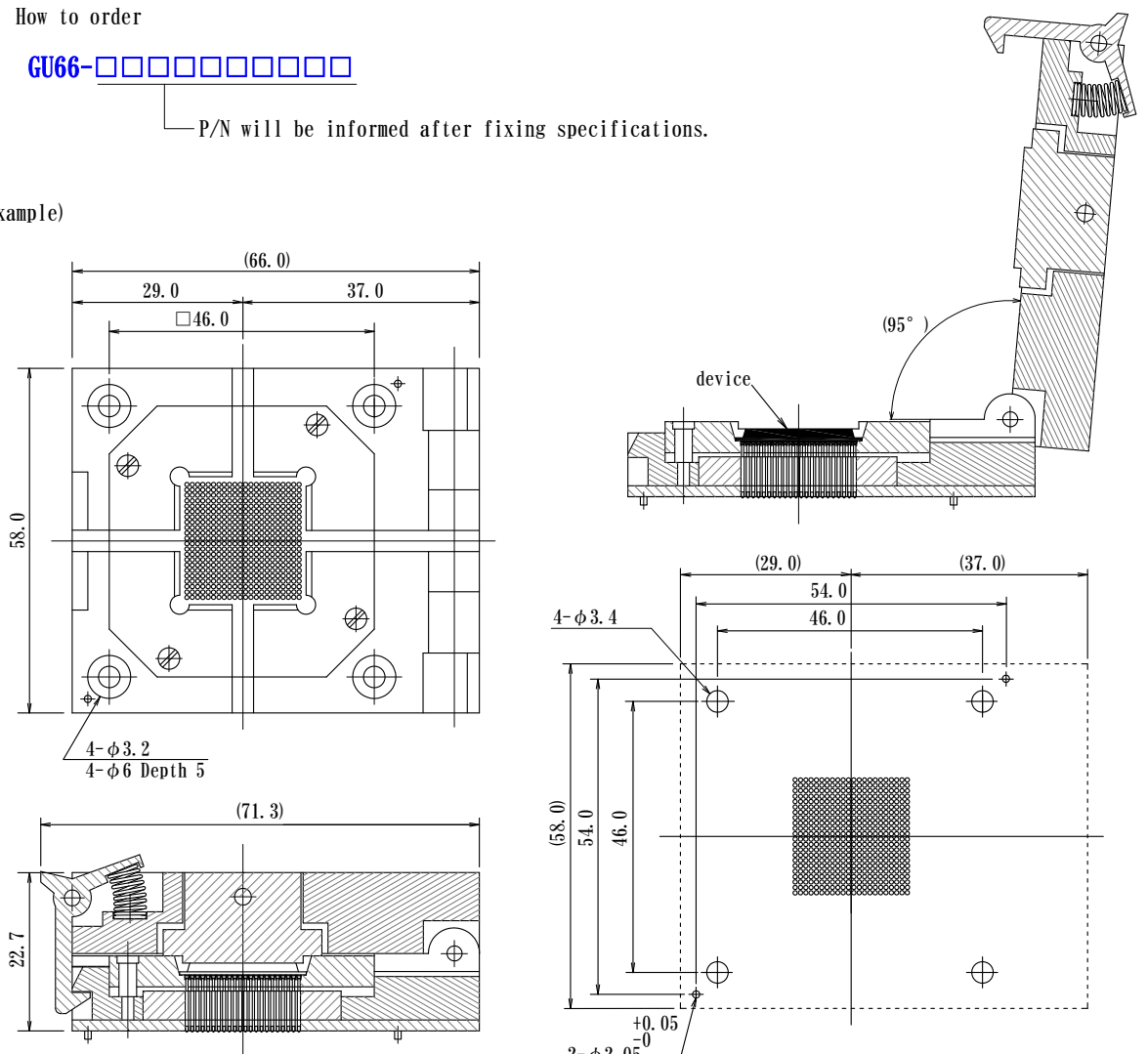


How to order

**GU66-□□□□□□□□□□**

P/N will be informed after fixing specifications.

example)



Dimensions (mm):

- Overall width: 66.0
- Left section width: 29.0
- Right section width: 37.0
- Device area width: 46.0
- Overall height: 58.0
- Bottom section width: 71.3
- Bottom section height: 22.7
- Device height: 46.0
- Device area height: 54.0
- Device area width: 46.0
- Pin diameter: 4-φ3.2
- Pin depth: 4-φ6 Depth 5
- Pin diameter: 4-φ3.4
- Pin diameter: 2-φ2.05 (+0.05/-0)
- Angle: 95°

PCB Pattern (Top View)

mm